

Text Search application # 101781,169

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	15	(substrate or board) and (solder adj mask or solder adj resist) and (underfill or resin adj sealing or resin adj filling) and (dummy adj pattern or dummy adj trace)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 09:04
L3	94	(substrate or board) and (solder adj mask or solder adj resist) and (underfill or resin adj sealing or resin adj filling) and (dummy)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 09:04
L4	79	3 not 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 09:12
S8	2	((substrate) with (solder adj mask or solder adj resist) with (under\$1fill)).clm.	US-PGPUB	OR	ON	2005/12/08 17:24
S9	1	((substrate) with (solder adj mask or solder adj resist) with (under\$1fill)).ab.	US-PGPUB	OR	ON	2005/12/08 17:29
S13	2	((die or chip or semiconductro adj device) with (solder adj mask or solder adj resist) with (under\$1fill)).ab.	US-PGPUB	OR	ON	2005/12/08 17:26
S14	1	((die or chip or semiconductro adj device) with (solder adj mask or solder adj resist) with (under\$1fill)).clm.	US-PGPUB	OR	ON	2005/12/08 17:26
S15	35	((die or chip or semiconductro adj device) with (solder adj mask or solder adj resist) with (under\$1fill))	US-PGPUB	OR	ON	2005/12/08 17:29
S16	6	((pcb or pwb or board) with (solder adj mask or solder adj resist) with (under\$1fill))	US-PGPUB	OR	ON	2005/12/08 17:30
S17	6202	underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/08 17:30

S18	54526	(chip or package or IC or die) with (substrate or board) and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/08 17:31
S19	3985	S17 and S18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/08 17:31
S20	252907	(arm or channel or groove) with (metal or copper)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/08 17:32
S21	14518	(arm or channel or groove) with (metal or copper) with (board or substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/08 17:41
S22	29	S19 and S21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/08 17:52
S23	68388	S18 or S21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/08 17:41
S24	4289	S23 and under\$1fill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/08 17:42
S25	2432	S24 and (solder adj bump\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/08 17:43

S26	67	S25 and ((shape) near3 (x or cross))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/08 17:45
S28	310	(substrate) and (chip) and (channel) and (solder) and (bump) and (underfill)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 12:09
S29	11	S28 and (S22 or S26)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/08 17:54
S30	4635	(package) and (substrate or board) and (underfill\$4 or resin adj fill\$4) and (solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/08 17:56
S31	1043	(package) and (substrate or board) and (underfill\$4 or resin adj fill\$4) and (solder) and (arm or channel or groove)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/08 17:56
S32	743	(package) and (substrate or board) and (underfill\$4 or resin adj fill\$4) and (solder) and (arm or channel or groove) and (bump\$)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/08 17:57
S52	1360	((substrate or board) and (chip or ic or die or integrated adj circuit or semiconductor or package) and (under\$1fill and resin near3 fill\$ or seal\$4 near3 resin)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 12:23
S53	8680	((substrate or board) and (chip or ic or die or integrated adj circuit or semiconductor or package) and (under\$1fill and resin near3 fill\$ or seal\$4 near3 resin)).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 12:29

S56	98599	(under\$1fill) or (resin near3 filling) or (seal\$4 near3 resin)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 12:28
S57	22529	S56 and((substrate or board) with (chip or ic or die or integrated adj circuit or semiconductor or package))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 12:30
S58	558	S56 and ((metal or copper) with (channel))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 12:30
S59	239	S57 and S58	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 12:30
S60	234	S59 not (S54 or S55 or S51)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 12:32
S77	8904	(underfill or resin near3 seal\$4) and (substrate or board or carrier) and (die or chip or ic or integrated adj circuit or semiconductor adj device or electronic adj component).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:26
S78	16621	(underfill or resin near3 seal\$4) and (substrate or board or carrier) and (die or chip or ic or integrated adj circuit or semiconductor adj device or electronic adj component).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:27
S79	7312	S77 and S78	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:27

S80	1240	S79 and (solder adj mask or solder adj resist)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:31
S81	4	S79 and ((solder adj mask or solder adj resist) with (partition or dividing))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/09 17:30
S87	1	(trace) and (mask or resist or resin) and (underfill) and (X adj shape or Cross adj shape)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/10 08:58
S88	11362	(X adj shape or Cross adj shape)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/10 08:58
S89	6882	(X adj shape or Cross adj shape) and (pattern or structure or wiring or circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/10 08:59
S90	2520	S89 and (board or substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/10 08:59
S91	1303	S90 and (chip or die or ic or integrated adj circuit or semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/10 09:41
S92	5	(underfill or underfilling) with (efficiency) with (substrate or board) with (flip adj chip\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/10 14:48



S93	10	(underfill or underfilling) with (efficien\$6) with (substrate or board) with (flip adj chip\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/10 14:42
S94	5	S93 not S92	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/10 14:49
S95	94	(underfill or underfilling) same (efficien\$6) same (substrate or board) same (flip adj chip\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/10 14:54
S96	84	S95 not (S93 or S92)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/10 14:54
S97	1210	(underfill or underfilling) and (efficien\$6) and (substrate or board) and (flip adj chip\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/10 14:54
S98	1116	S97 not (S95 or S93 or S92)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/10 15:24
S100	1	(substrate or board) with (underfill or resin adj sealing or resin adj filling) with (arm\$1).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/11 18:48
S103	327	(substrate or board) and (underfill or resin adj sealing or resin adj filling) and (arm\$1) and (shape)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/11 18:56